

# Hyperfast Rectifier, 2 A FRED Pt®



SMA (DO-214AC)



## FEATURES

- Hyperfast recovery time, reduced  $Q_{rr}$ , and soft recovery
- 175 °C maximum operating junction temperature
- Specified for output and snubber operation
- Low forward voltage drop
- Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Meets JESD 201 class 2 whisker test
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

## LINKS TO ADDITIONAL RESOURCES



## PRIMARY CHARACTERISTICS

$I_{F(AV)}$	2 A
$V_R$	200 V
$V_F$ at $I_F$	0.75 V
$t_{rr}$	25 ns
$T_J$ max.	175 °C
Package	SMA (DO-214AC)
Circuit configuration	Single

## DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers specifically designed with optimized performance of forward voltage drop and hyperfast recovery time.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness, and reliability characteristics.

These devices are intended for use in snubber, boost, lighting, as high frequency rectifiers, and freewheeling diodes.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element.

## MECHANICAL DATA

**Case:** SMA (DO-214AC)

Molding compound meets UL 94 V-0 flammability rating  
Halogen-free, RoHS-compliant

**Terminals:** matte tin plated leads, solderable per J-STD-002

**Polarity:** color band denotes cathode end

## ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage	$V_{RRM}$		200	V
Average rectified forward current	$I_{F(AV)}$	$T_{Sp} = 138$ °C	2	A
Non-repetitive peak surge current	$I_{FSM}$	$T_J = 25$ °C, 6 ms square pulse	50	
Operating junction and storage temperatures	$T_J, T_{Stg}$		-55 to +175	°C

## ELECTRICAL SPECIFICATIONS ( $T_J = 25$ °C unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	$V_{BR}, V_R$	$I_R = 100$ $\mu$ A	200	-	-	V
Forward voltage, per diode	$V_F$	$I_F = 2$ A	-	0.88	0.95	
		$I_F = 2$ A, $T_J = 125$ °C	-	0.75	0.82	
Reverse leakage current, per diode	$I_R$	$V_R = V_R$ rated	-	-	2	$\mu$ A
		$T_J = 125$ °C, $V_R = V_R$ rated	-	1	8	
Junction capacitance	$C_T$	$V_R = 200$ V	-	8	-	pF

**DYNAMIC RECOVERY CHARACTERISTICS** ( $T_J = 25\text{ }^{\circ}\text{C}$  unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	$t_{rr}$	$I_F = 1\text{ A}$ , $dI_F/dt = 50\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$	-	24	-	ns
		$I_F = 0.5\text{ A}$ , $I_R = 1\text{ A}$ , $I_{rr} = 0.25\text{ A}$	-	-	25	
		$T_J = 25\text{ }^{\circ}\text{C}$	-	16	-	
		$T_J = 125\text{ }^{\circ}\text{C}$	-	22	-	
Peak recovery current	$I_{RRM}$	$T_J = 25\text{ }^{\circ}\text{C}$	-	2	-	A
		$T_J = 125\text{ }^{\circ}\text{C}$	-	3	-	
Reverse recovery charge	$Q_{rr}$	$T_J = 25\text{ }^{\circ}\text{C}$	-	16	-	nC
		$T_J = 125\text{ }^{\circ}\text{C}$	-	30	-	

**THERMAL - MECHANICAL SPECIFICATIONS**

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	$T_J, T_{Stg}$		-55	-	175	$^{\circ}\text{C}$
Thermal resistance, junction to mount	$R_{thJM}$	Device mounted on PCB with 2 x 3.5 mm soldering lands	-	11	21	$^{\circ}\text{C}/\text{W}$
Thermal resistance, junction to ambient	$R_{thJA}$	Device mounted on PCB with recommended pad size	-	-	125	$^{\circ}\text{C}/\text{W}$
Approximate weight			0.07			g
			0.002			oz.
Marking device		Case style SMA (DO-214AC)	2H2			

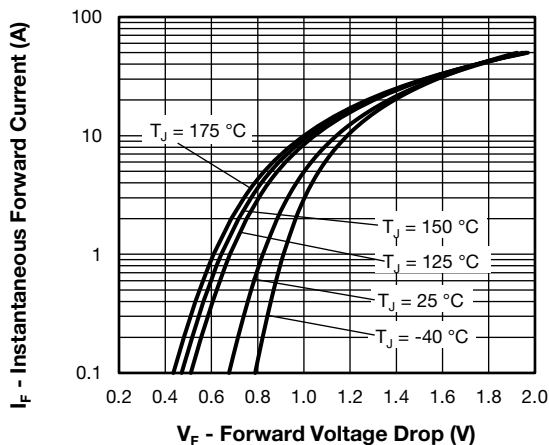


Fig. 1 - Typical Forward Voltage Drop Characteristics

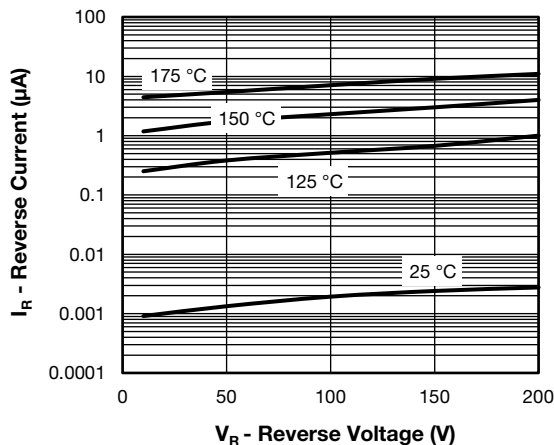


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

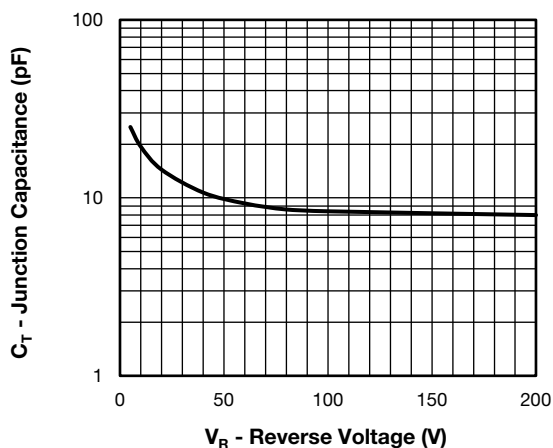


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

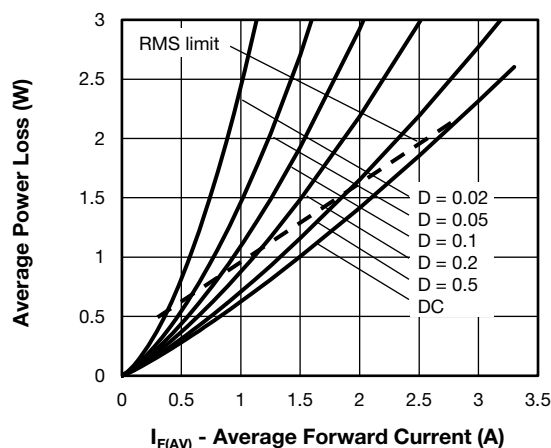


Fig. 5 - Forward Power Loss Characteristics

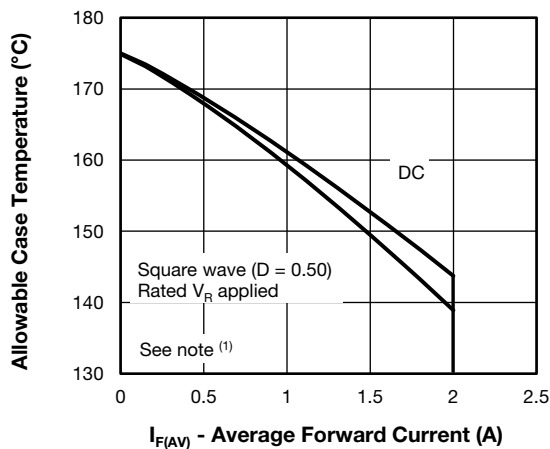
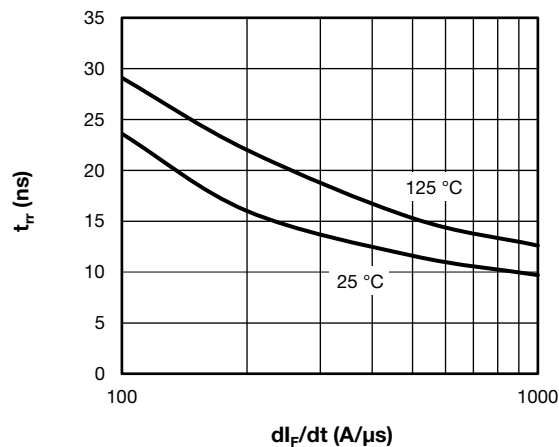
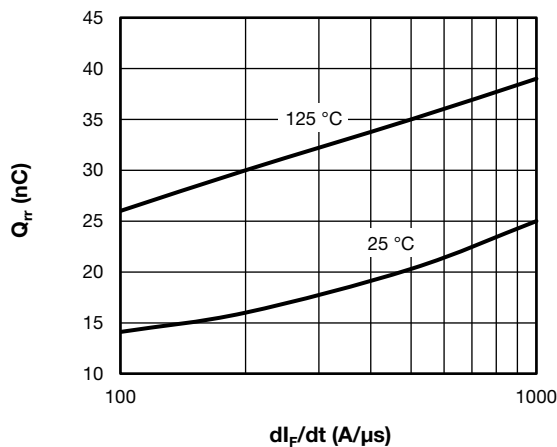


Fig. 4 - Maximum Allowable Case Temperature vs. Average Forward Current


Fig. 6 - Typical Reverse Recovery Time vs.  $dI_F/dt$ 

Fig. 7 - Typical Stored Charge vs.  $dI_F/dt$ 

#### Note

- (1) Formula used:  $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$ ;  
 $P_d$  = forward power loss =  $I_{F(AV)} \times V_{FM}$  at  $(I_{F(AV)}/D)$  (see fig. 5);  
 $P_{dREV}$  = inverse power loss =  $V_{R1} \times I_R (1 - D)$ ;  $I_R$  at  $V_{R1}$  = rated  $V_R$

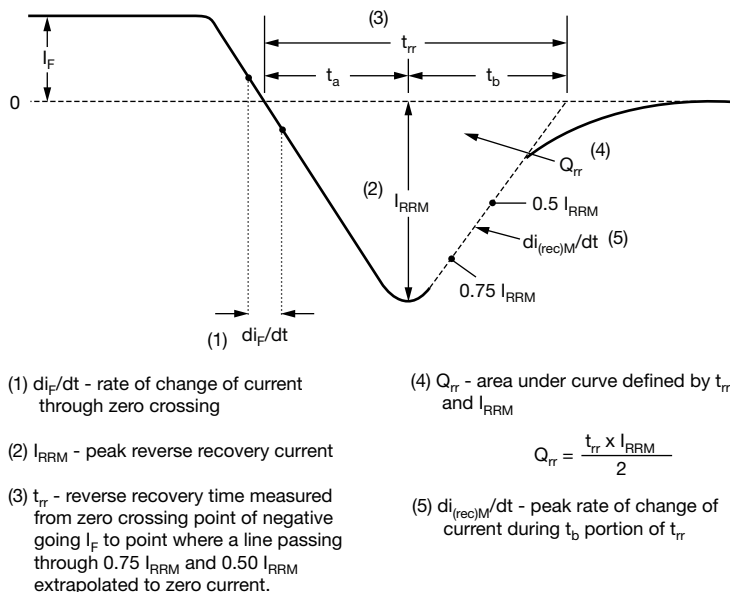


Fig. 8 - Reverse Recovery Waveform and Definitions

## ORDERING INFORMATION TABLE

Device code	VS-	2	E	M	H	02	-M3
	1	2	3	4	5	6	7

- 1** - Vishay Semiconductors product
- 2** - Current rating (2 = 2 A)
- 3** - Circuit configuration:  
E = single diode
- 4** - M = SMA package
- 5** - Process type,  
H = hyperfast recovery
- 6** - Voltage code (02 = 200 V)
- 7** - -M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

### ORDERING INFORMATION (Example)

PREFERRED P/N	QUANTITY PER REEL	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-2EMH02-M3/5AT	7500	7500	13" diameter plastic tape and reel

### LINKS TO RELATED DOCUMENTS

Dimensions	<a href="http://www.vishay.com/doc?95400">www.vishay.com/doc?95400</a>
Part marking information	<a href="http://www.vishay.com/doc?95472">www.vishay.com/doc?95472</a>
Packaging information	<a href="http://www.vishay.com/doc?95404">www.vishay.com/doc?95404</a>
SPICE model	<a href="http://www.vishay.com/doc?96376">www.vishay.com/doc?96376</a>

## SMA

**DIMENSIONS** in inches (millimeters)

**DO-214AC (SMA)**



**Mounting Pad Layout**





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